



IAC-RV1126B-Kit Hardware Manual

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Company Profile

Zhejiang Qiyang Intelligent Technology Co., Ltd., established in 2007, which locates in Hangzhou, Zhejiang, PRC. It is a high-end technological enterprise that specializes in exploitation, fabrication, and selling embedded computer mainboards. With almost 20 years of experiences, Qiyang has established the completed service chain from the design concept to mass production successfully.

The R&D team is organized by 30 more technical engineers. Qiyang focus on providing functional embedded hardware, software tool and customization solutions. It has been applied to Industrial Control, Internet of Things, New Retail, Smart Medical, Electricity Device, Environmental Surveillance, Charging Pile etc.

With the growth of the business, Qiyang has set up an SMT factory in Zhuji, Zhejiang province, which is 5000 m², with a 3xSMT production line. The SMT factory performs the ISO9001 Quality Management System strictly. Relying on the solid production ability, the SMT factory's annual capacity is about a million sets, which totally guarantee the delivery date.

Qiyang has a thorough sales marketing network, professional sales ,and after-sales team to provide full technical support and service. The business has spread over 120 countries and areas, it helps the clients to introduce the products into the market efficiently and successfully. The combination and extension of research and development, production capacity, and market, that provide a solid foundation for Qiyang to provide specialized, globalized embedded hardware and software.

We offer:

1. Software/Hardware Mainboard

Based on the CPU solution from NXP, Rockchip, MTK, Renesas, TI, Atmel, Cirrus Logic etc, Qiyang provides the ARM development kit/system on module/industrial board and periphery products, paired tools and software for the user do further exploitation.

2. Customization Service

Fully taking the advantage of the technical accumulation on the ARM platform and Linux, Android, Ubuntu OS, Qiyang provides the efficient OEM/ODM service to the users.

Sincerely thanks for using Qiyang's product, we will try our best to offer you the technical supports!

IAC-RV1126B-Kit Development Board Use Suggestion:

1. Please read the instructions before using the IAC-RV1126B-Kit development Kit;
2. Before using, please check the packing list and see whether there is a missing file in the folder;
3. Please understand the basic structure and composition of IAC-RV1126B-CM SOM, including the hardware resource allocation, and expansion pin definition, etc.;
4. If you want to develop based on Debian Linux or Android OS, to flash the program on the development board, we suggest you to read another article ***IAC-RV1126B -Kit User Manual***.
5. IAC-RV1126B-CM SOM module accept batch orders.

Technical Support

If you have questions about the documents, you can contact us during office hours (Monday to Friday 8:30-12:00, 13:30-17:30)

Contact us at

Technical Email: supports@qiyangtech.com

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Official website: [www.qiytech.com\(Chinese\)](http://www.qiytech.com(Chinese)) / [www.qiyangtech.com\(English\)](http://www.qiyangtech.com(English))

Information updates

1. Information updates

Product-related manuals and datasheets are constantly being improved and updated; please ensure that they are up-to-date when you use them.

2.Update notice

Qiyang's newest product information and news updates will be released through



the WeChat official account, please pay attention!

3. How to get information

After purchase, please contact the relevant sales staff to obtain the SDK.

4. Provided materials

Software: factory image, related kernel source code, interface test source code, cross compiler

Hardware: corresponding baseboard schematic, PCB source file (Allegro16.6)

Files: hardware manual, test manual, user manual, environment construction manual, IO pin comparison table, core board, baseboard structure dimension drawing (dxf), chip information.

Usage suggestions:

- 1) before using the development board, be sure to read the hardware manual first;
- 2) please check the packing list carefully before use and check whether there are any missing files;
- 3) understand the basic structure and composition of the development kit, including the allocation of hardware resources, the definition of each pin of the core board and the carrier board, and the definition of the expansion pins, etc.;
- 4) if you need to burn an image, test the development kit functions, you also need to read the user manual and test manual;
- 5) we accept bulk orders for the IAC-RV1126B -Kit development kit.

Version Record

Version No.	Hardware Platform	Date	Description	Revised by
V1.0	SCH-IAC-RV1126B-MB-V1_00 SCH-IAC-RV1126B-CM-V1_00	2025-12	Initial Version	Maoh

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ATTN: This manual introduces the hardware interface of the IAC-RV1126B-Kit Development Kit.

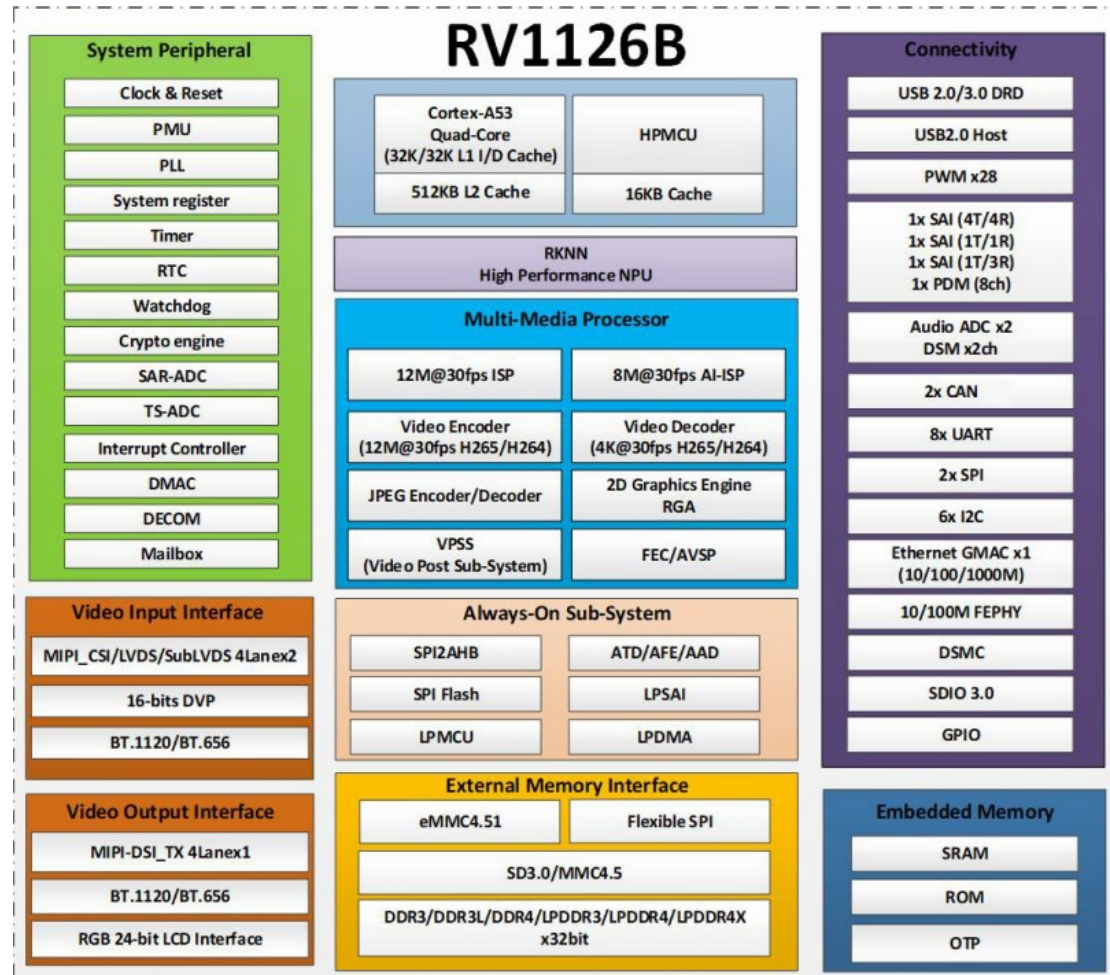
I. System Composition

1.1.Overview

RV1126B is a high-performance vision processor SoC for machine vision application, especially for AI related application. It is based on quad-core ARM Cortex-A53 64-bit core which integrates NEON and FPU. There is a 32KB I-cache and 32KB D-cache for each core and 512KB unified L2 cache. The build-in NPU Support INT8/INT16 hybrid operation and computing power is up to 3.0TOPs. In addition, with its strong compatibility, network models based on a series of frameworks such as TensorFlow/MXNet/PyTorch/Caffe can be easily converted. RV1126B introduces a new generation totally hardware-based maximum 12-Megapixel ISP (image signal processor) and post processor. It implements a lot of algorithm accelerators, such as HDR, 3A, LSC, 3DNR, 2DNR, sharpening, dehaze, fisheye correction, gamma correction, feature points detection and so on. A maximum 8-Megapixel AI-ISP is also introduced as a complement to traditional ISP, which offers superior spatial denoising performance and enhanced image enhancement effects. Cooperating with two MIPI CSI(or LVDS/SubLVDS) and one DVP(BT.601/BT.656/BT.1120) interface, users can build a system that receives video data from four camera sensors simultaneously. The video encoder embedded in RV1126B support H.265/H.264 video encoding and the multi-stream encoding is supported also. With the help of this feature, the video from camera can be encoded with higher resolution and stored in local memory and transferred another lower resolution video to cloud storage at the same time.

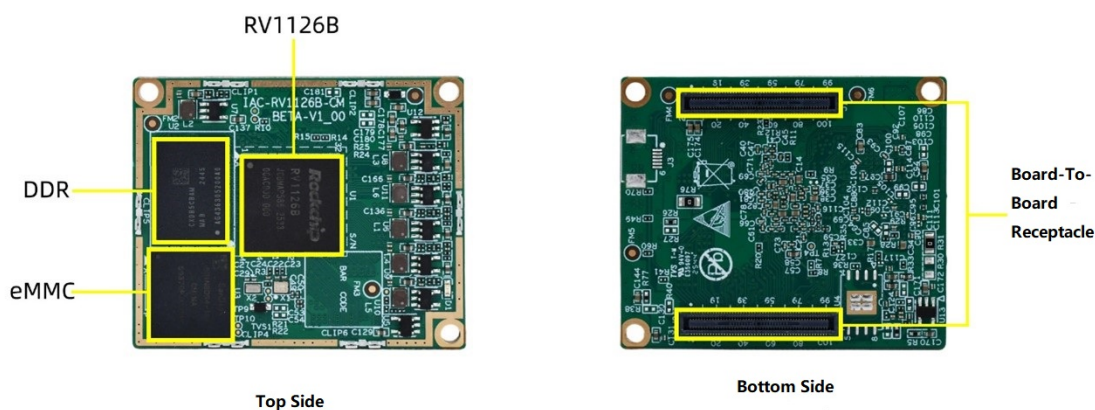
The H.264/H.265 video decoder in RV1126B support 4Kp30 for H.264 and H.265. In addition to the previous high-performance multimedia block, RV1126B also contains rich audio, memory and other peripheral interfaces such as I2C, SPI, PWM and so on. These can help users add more sensors or other peripherals into whole system to improve flexibility and expansibility. RV1126B has high-performance external DRAM(DDR3/DDR3L/DDR4/LPDDR3/LPDDR4/4X) capable of sustaining demanding memory bandwidths. Also the RTC, POR, RMII Ethernet PHY and Audio Codec are integrated in RV1126B.

RV1126B Processor Block Diagram::



1.2.SOM Resource Overview

IAC-RV1126B-CM SOM module adopts 8-layer PCB high precision immersion gold process, high TG board, with reliable electricity and anti-interference performance. Integrated with CPU,LPDDR4,eMMC, etc. It adopts Board-To-Board receptacles which has derived 200 pins from the SOM module. It fully extended RV1126B processor resources, and it is available to design a tailored carrier board based on the multiplexed pins.



- ◆ Onboard with RockChip RV1126B processor
- ◆ Onboard with 4GB LPDDR4,16GB eMMC (Std.)
- ◆ SOM adapts 8-lay PCB high precision immersion gold technology;
- ◆ SOM Size: 40mm*47mm, it suits for various application scenarios;
- ◆ The SOM has 2 pieces of 100pin board to board connector to derive SOM resources;
- ◆ +3.3VDC
- ◆ Linux6.1, Buildroot

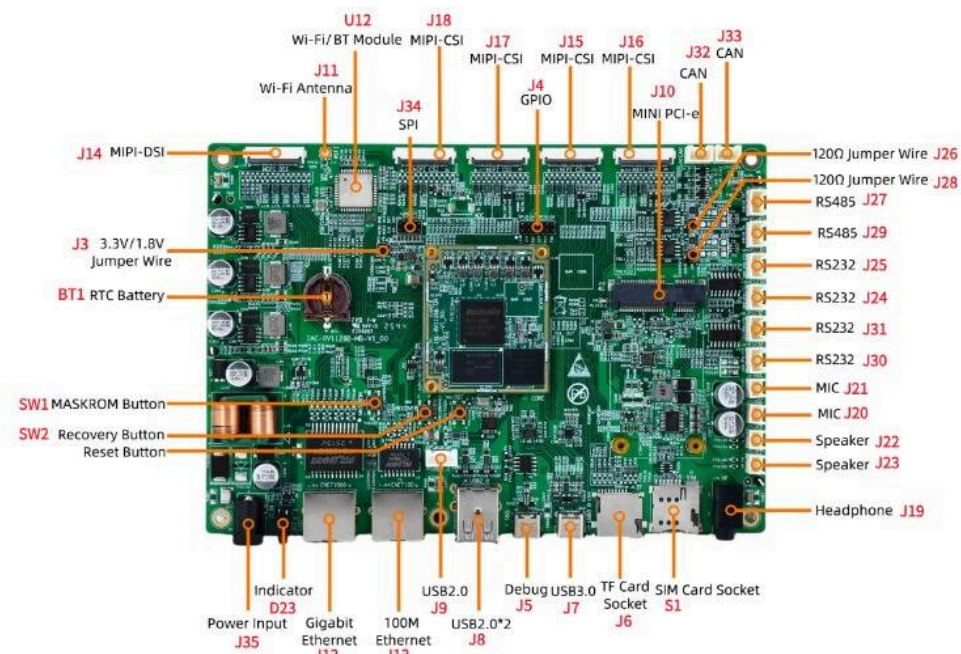
1.3. Development Board Resources

Hardware Resource	CPU	RockChip RV1126B
	Processor	Quad ARM® Cortex™-A53 RV1126B, the frequency is up to 1.5GHz
	RAM	4GB LPDDR4 (8GB optional)
	Flash	16GB (32GB、64GB optional)
	NPU	3 TOPS
	Ethernet	2x network chip, including 1-ch integrated with 100Mbps MAC+PHY, another one integrated with RGMII (Either-or, only 1xMAC)
	WLAN	Onboard with AP6256 Wi-Fi module, support 2.4Ghz/5Ghz 802.11 a/b/g/n protocol
	Connectivity	4x RS232 (3-wire serial interface, two of which are multiplexed with RS485)
		2x RS485 (3-wire serial port, multiplexed with RS232)
		2x CAN
	Display	1x 4-lane MIPI_DSI, 1080P@60fps
	Audio	1x balanced stereo amplifier output
		2x MIC Audio Input
		1x 3.5mm stereo output
	USB	3x USB2.0 HOST ; 2x Type-A ;1x PHB2.0
		1xUSB Type-C (Debug)
		1xUSB3.0 Type-C OTG
	Camera	4x MIPI-CSI 2Lane, single channel supports 1080P@30fps in max.
	Expansion	MINI-PCIE (USB2.0), to connect 4G , SIM card socket
	Others	SPI * 1
	Storage	1x TF card socket
	Other devices	Reset Circuit ,Watchdog, RTC
	Power Input	9V~36V, DC_12V (Std.)
Electronical Specification	Layer/Size	SOM Size:40mm*47mm 8-layer high precision immersion gold technology
		Carrier Board Size:125mm*180mm 4-layer high precision immersion gold technology
	Power Consumption	1.3W (Non-loaded)

	Working Temperature	-20℃ ~ +80℃
	Storage Temperature	-20℃ ~ +90℃
	Humidity	5%~50%,non-condensation
	Options	Std.: 4GB DDR/16GB eMMC (-20℃ ~ +80℃)
		8GB DDR/32GB eMMC (-20℃ ~ +80℃) (Optional)
		Meanwhile, the industrial grade (-40℃~+85℃)is selectable

II. Connectors on Carrier Board

➤ Block Diagram- Top View



2.1.Basic functions

Label	Functions
J35	DC12V power input
J12	Gigabit Ethernet
J13	100Mbps Ethernet
J9/J8	USB2.0
J5	USB Debug
J7	USB3.0 OTG
J6	TF Card
S1	SIM Card
J19	HeadPhone
J22/J23	Speaker
J20/J21	MIC
J30/J31/J24/J25	RS232
J27/J29	RS485
J26/J28	120Ω jumper wire
J33/J32	CAN
J10	MINI PCIE(USB2.0)
J16/J15/J17/J18	MIPI-CSI
J4	GPIO
J34	SPI
J14	MIPI-DSI
J3	3.3V/1.8V jumper wire

2.2.PIN Definition

J1A

Multiplexing GPIO	Signal Name	PIN#	PIN#	Single Name	Multiplexing GPIO
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	VCC_SYS_3V3	1	2	VCC_SYS_3V3	
	VCC_SYS_3V3	3	4	VCC_SYS_3V3	
	VCC_SYS_3V3	5	6	VCC_SYS_3V3	
	VCC_SYS_3V3	7	8	VCC_AUD_1V8	
	GND	9	10	GND	
	GND	11	12	GND	
	GND	13	14	GND	
	VCC_IO_SD0	15	16	VCC_IO_1V8	
	VCC_IO_SD1	17	18	VCC_IO_3V3	
	CM_PWR_CTRL	19	20	VCC_IO_3V3	
GPIO5_A7_D	I2C5_SDA	21	22	IO_EXT_PWREN	GPIO5_D3_D
GPIO5_A1_D	I2C5_SCL	23	24	IO_4G_PWREN	GPIO5_D2_D
GPIO5_B3_D	IO_LCD_TP_nINT	25	26	IO_4G_nRST	GPIO5_D1_D
GPIO5_B4_D	IO_LCD_TP_nRST	27	28	IO_4G_nDIS	GPIO5_D0_D
GPIO5_D6_U	CAN1_RXD	29	30	SPI0_MISO	GPIO5_A5_D
GPIO5_D7_U	CAN1_TXD	31	32	SPI0_MOSI	GPIO5_A4_D
GPIO5_D4_U	GPIO5_D4_U	33	34	SPI0_CLK	GPIO5_A6_D
GPIO5_D5_U	GPIO5_D5_U	35	36	SPI0_nCS	GPIO5_A3_D
GPIO5_B6_D	GMAC_MDC	37	38	IO_CAN_STBY	GPIO5_A2_D
GPIO5_B5_D	GMAC_MDIO	39	40	IO_ENET1_nRST	GPIO5_C1_D
GPIO5_B7_D	GMAC_TXD0	41	42	GMAC_RXD0	GPIO5_B1_D
GPIO5_C0_D	GMAC_TXD1	43	44	GMAC_RXD1	GPIO5_B2_D
GPIO5_C5_D	GMAC_TXD2	45	46	GMAC_RXD2	GPIO5_C3_D
GPIO5_A0_D	GMAC_TXD3	47	48	GMAC_RXD3	GPIO5_C4_D
GPIO5_C2_D	GMAC_TXCTL	49	50	GMAC_RXCTL	GPIO5_B0_D
GPIO5_C6_D	GMAC_TXCLK	51	52	GMAC_RXCLK	GPIO5_C7_D
	GND	53	54	GND	

	MIPI_TX_D3P	55	56	SDMMC1_CLK	GPIO3_A0_D
	MIPI_TX_D3N	57	58	SDMMC1_D1	GPIO3_A3_D
	MIPI_TX_D2P	59	60	SDMMC1_D0	GPIO3_A2_D
	MIPI_TX_D2N	61	62	SDMMC1_CMD	GPIO3_A1_D
	MIPI_TX_CLKP	63	64	SDMMC1_D3	GPIO3_A5_D
	MIPI_TX_CLKN	65	66	SDMMC1_D2	GPIO3_A4_D
	MIPI_TX_D1P	67	68	GND	
	MIPI_TX_D1N	69	70	UART2_RXD	GPIO3_B0_D
	MIPI_TX_D0P	71	72	UART2_TXD	GPIO3_B1_D
	MIPI_TX_D0N	73	74	UART2_nCTS	GPIO3_A7_D
	GND	75	76	UART2_nRTS	GPIO3_A6_D
	FEPHY_TXP	77	78	IO_BT_nRST	GPIO3_B5_D
	FEPHY_TXN	79	80	IO_BT_nINT	GPIO3_B2_D
	FEPHY_RXP	81	82	IO_WIFI_nRST	GPIO3_B4_D
	FEPHY_RXN	83	84	IO_WIFI_nINT	GPIO3_B3_D
	GND	85	86	IO_WL_PWREN	GPIO3_B6_D
GPIO0_C2_U	I2C0_SCL	87	88	IO_RUN_LED	GPIO3_B7_D
GPIO0_C3_U	I2C0_SDA	89	90	GND	
GPIO0_D0_D	I2C2_SCL	91	92	SARADC0_IN7	
GPIO0_D1_D	I2C2_SDA	93	94	SARADC0_IN0	
GPIO0_C0_D	IO_LCD_BL_EN	95	96	GND	
GPIO0_C1_D	IO_LCD_nRST	97	98	UART0_RXD_DBG	
GPIO0_C7_D	PWM0_OUT	99	100	UART0_TXD_DBG	

J1B

Multiplexing GPIO	Signal Name	PIN#	PIN#	Single Name	Multiplexing GPIO
GPIO6_C2_D	UART3_TXD	1	2	UART7_TXD	GPIO6_B4_D

GPIO6_C3_D	UART3_RXD	3	4	UART7_RXD	GPIO6_B5_D
GPIO6_C0_D	UART3_nRTS	5	6	UART7_nRTS	GPIO6_B6_D
GPIO6_C1_D	IO_CAM3_PWREN	7	8	IO_CAM1_PWREN	GPIO6_B7_D
GPIO6_A2_D	UART5_TXD	9	10	UART6_TXD	GPIO6_B0_D
GPIO6_A3_D	UART5_RXD	11	12	UART6_RXD	GPIO6_B1_D
GPIO6_A4_D	IO_CAM3_nRST	13	14	IO_CAM1_nRST	GPIO6_B2_D
GPIO6_A5_D	IO_CAM3_PWDN	15	16	IO_CAM1_PWDN	GPIO6_B3_D
GPIO6_A0_D	IO_CAM4_PWREN	17	18	IO_CAM2_PWREN	GPIO6_A6_D
GPIO6_A1_D	IO_CAM4_nRST	19	20	IO_CAM2_nRST	GPIO6_A7_D
	GND	21	22	GND	
	MIPI_RX1_D0N	23	24	MIPI_RX0_D0N	
	MIPI_RX1_D0P	25	26	MIPI_RX0_D0P	
	MIPI_RX1_D1N	27	28	MIPI_RX0_D1N	
	MIPI_RX1_D1P	29	30	MIPI_RX0_D1P	
	MIPI_RX1_CLK0N	31	32	MIPI_RX0_CLK0N	
	MIPI_RX1_CLK0P	33	34	MIPI_RX0_CLK0P	
	MIPI_RX1_CLK1N	35	36	MIPI_RX0_CLK1N	
	MIPI_RX1_CLK1P	37	38	MIPI_RX0_CLK1P	
	MIPI_RX1_D3N	39	40	MIPI_RX0_D3N	
	MIPI_RX1_D3P	41	42	MIPI_RX0_D3P	
	MIPI_RX1_D2N	43	44	MIPI_RX0_D2N	
	MIPI_RX1_D2P	45	46	MIPI_RX0_D2P	
	GND	47	48	GND	
GPIO4_A1_U	CAM_CLK2_OUT	49	50	CAM_CLK0_OUT	GPIO4_B1_D
GPIO4_A0_U	CAM_CLK3_OUT	51	52	CAM_CLK1_OUT	GPIO4_B0_D
GPIO4_A7_D	I2C4_SCL_1V8	53	54	I2C3_SCL_1V8	GPIO4_A4_D
GPIO4_A6_D	I2C4_SDA_1V8	55	56	I2C3_SDA_1V8	GPIO4_A5_D

GPIO4_A3_D	IO_CAM4_PWDN	57	58	IO_CAM2_PWDN	GPIO4_A2_D
	GND	59	60	GND	
GPIO2_A4_D	SDMMC0_CLK	61	62	IO_AMP_PWREN	GPIO7_A4_D
GPIO2_A0_D	SDMMC0_D0	63	64	IO_AMP_EN	GPIO7_A1_D
GPIO2_A1_D	SDMMC0_D1	65	66	SAI0_MCLK	GPIO7_A2_D
GPIO2_A5_D	SDMMC0_CMD	67	68	SAI0_SCLK	GPIO7_A0_D
GPIO2_A2_D	SDMMC0_D2	69	70	SAI0_LRCK	GPIO7_A3_D
GPIO2_A3_D	SDMMC0_D3	71	72	SAI0_SDO0	GPIO7_A5_D
GPIO0_A5_U	SDMMC0_DET	73	74	SAI0_SDI0	GPIO7_A6_D
	GND	75	76	IO_AUD_HP_DET	GPIO7_A7_D
	MIC_IN0N	77	78	DSM_AUD_RP	GPIO7_B1_D
	MIC_IN0P	79	80	DSM_AUD_RN	GPIO7_B0_D
	GND	81	82	GND	
GPIO0_A6_U	SDMMC0_VSELECT	83	84	USB_HOST_DP	
	IO_HUB_nRST	85	86	USB_HOST_DM	
GPIO0_C2_U	IO_TYPEC_PWREN	87	88	USB_DRD_SSRXN	
GPIO0_C3_U	IO_TYPEC_CH_SEL	89	90	USB_DRD_SSRXP	
GPIO0_D0_D	IO_TYPEC_nINT	91	92	USB_DRD_SSTXN	
GPIO0_D1_D	IO_WDT_EN	93	94	USB_DRD_SSTXP	
GPIO0_C0_D	IO_WDT_FEED	95	96	USB_DRD_DP	
GPIO0_C1_D	GND	97	98	USB_DRD_DM	
GPIO0_C7_D	SYS_nRST	99	100	USB_DRD_VDET	

J23: Speaker

PIN#	Signal Name
1	AMP_SPK_OUTNR
2	AMP_SPK_OUTPR

J22: Speaker

PIN#	Signal Name
1	AMP_SPK_OUTPL
2	AMP_SPK_OUTNL

J20: MIC

PIN#	Signal Name
1	MIC_IN1P
2	MIC_IN1N

J21: MIC

PIN#	Signal Name
1	MIC_IN0P
2	MIC_IN0N

J30/J31/J24/J25: RS232

PIN#	Signal Name
1	COM_TXD
2	COM_RXD
3	GND

J29/J27: RS485

PIN#	Signal Name
1	RS485_A
2	RS485_B
3	GND

J32/J33: CAN

PIN#	Signal Name
1	CAN_H
2	CAN_L

3	GND
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J14: MIPI-DSI

Signal Name	PIN#	PIN#	Signal Name
VCC_EXT_5V0	1	2	VCC_EXT_5V0
VCC_EXT_5V0	3	4	VCC_EXT_5V0
GND	5	6	GND
IO_LCD_TP_nINT	7	8	IO_LCD_TP_nRST
I2C2_SDA	9	10	I2C2_SCL
GND	11	12	IO_LCD_BL_PWREN
LCD_PWM_OUT	13	14	IO_LCD_nRST
GND	15	16	MIPI_DSI_D0_N
MIPI_DSI_D0_P	17	18	GND
MIPI_DSI_D1_N	19	20	MIPI_DSI_D1_P
GND	21	22	MIPI_DSI_CLK_N
LCD_DSI_CLKP	23	24	GND
LCD_MIPI_D2N	25	26	LCD_MIPI_D2P
GND	27	28	LCD_MIPI_D3N
LCD_MIPI_D3P	29	30	GND

J15/J16/J17/J18: MIPI-CSI

PIN#	Signal Name
1	GND
2	MIPI_CLKP
3	MIPI_CLKN
4	GND
5	NC
6	NC

7	GND
8	MIPI_D0P
9	MIPI_D0N
10	GND
11	NC
12	NC
13	GND
14	MIPI_D1P
15	MIPI_D1N
16	GND
17	SID
18	GND
19	CAM_PWDN
20	CAM_nRST
21	CAM_I2C_SDA
22	CAM_I2C_SCL
23	VCC_CAM_1V2
24	GND
25	CAM_MCLK
26	GND
27	VCC_CAM_1V8
28	GND
29	VCC_CAM_2V8
30	VCC_CAM_2V8

J9: USB2.0 PHB HOST

PIN#	Signal Name
1	VCC_USB3_5V0

2	USB2_HOST1_DM
3	USB2_HOST1_DP
4	GND

J4: GPIO

Signal Name	PIN#	PIN#	Signal Name
FEPHY_LINK_LED	1	2	GPIO5_D4_U
IO_SPI_nINT	3	4	GPIO5_D4_U
CAN0_RXD	5	6	GPIO5_D4_U
FEPHY_ACT_LED	7	8	GPIO5_D5_U
IO_SPI_nRST	9	10	GPIO5_D5_U
CAN0_TXD	11	12	GPIO5_D5_U

J10: MINI-PCIE

Signal Name	PIN#	PIN#	Signal Name
NC	1	2	VCC_4G_3V3
NC	3	4	GND
NC	5	6	NC
NC	7	8	4G_UIM_PWR
GND	9	10	4G_UIM_DATA
NC	11	12	4G_UIM_CLK
NC	13	14	4G_UIM_nRST
GND	15	16	NC
NC	17	18	GND
NC	19	20	4G_nDISEN
GND	21	22	4G_nRST
NC	23	24	VCC_4G_3V3

NC	25	26	GND
GND	27	28	NC
GND	29	30	NC
NC	31	32	NC
NC	33	34	GND
GND	35	36	4G_USB_D_N
GND	37	38	4G_USB_D_P
VCC_4G_3V3	39	40	GND
VCC_4G_3V3	41	42	4G_STATE
GND	43	44	NC
NC	45	46	NC
NC	47	48	NC
NC	49	50	GND
NC	51	52	VCC_4G_3V3

J34: SPI

Signal Name	PIN#	PIN#	Signal Name
IO_SPI_nINT	1	2	SPI0_nCS
IO_SPI_nRST	3	4	SPI0_CLK
VCC_EXT_3V3	5	6	SPI0_MOSI
GND	7	8	SPI0_MISO

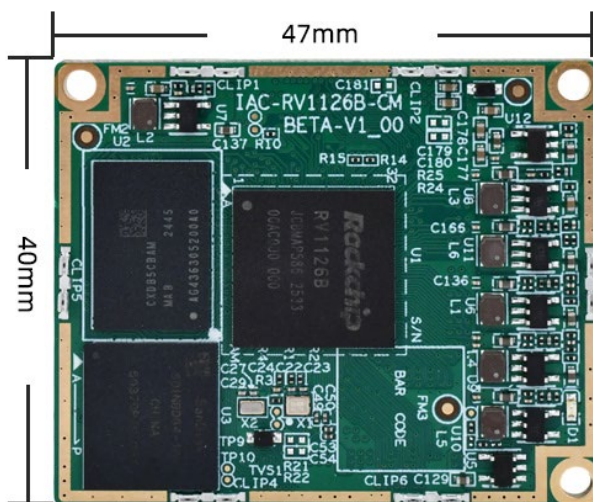
J3: 3.3V/1.8V jumper wire

Signal Name	PIN#	PIN#	Signal Name
VCC_IO_1V8	1	2	VCC_IO_SD0
VCC_IO_3V3	3	4	VCC_IO_SD0

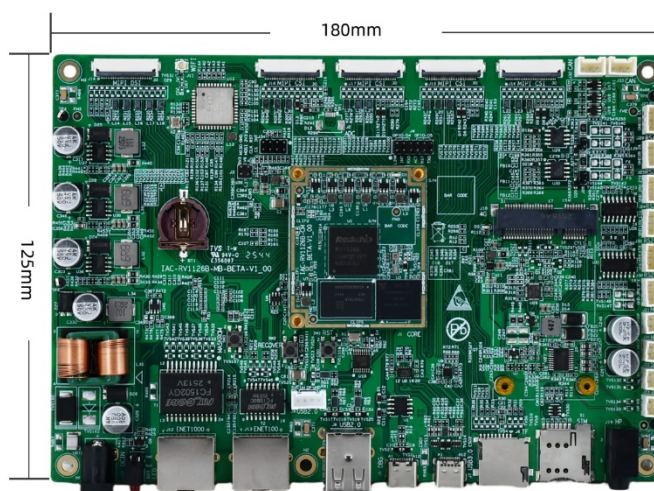
III. Size & Structure

Unit:mm, if needs the size of the board to board receptacle, please email:
supports@qiyangtech.com

3.1.Size of SOM Module

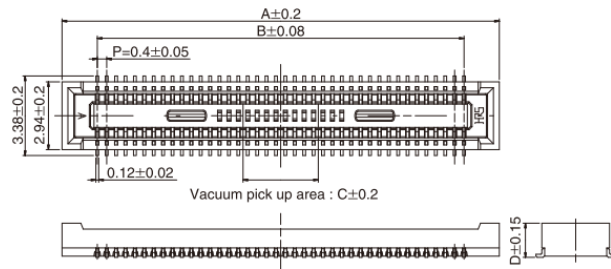
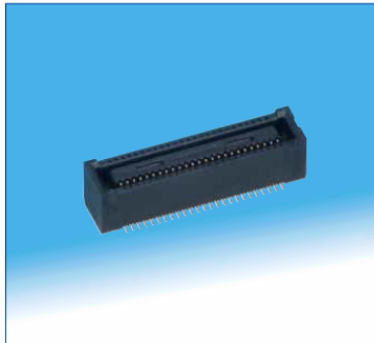


3.2.Size of Carrier Board

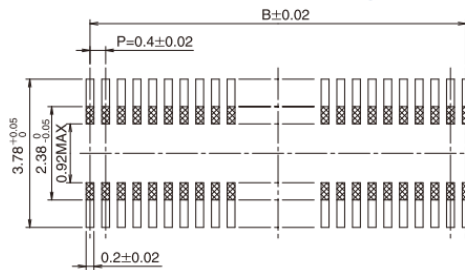


3.3 Size of the receptacle

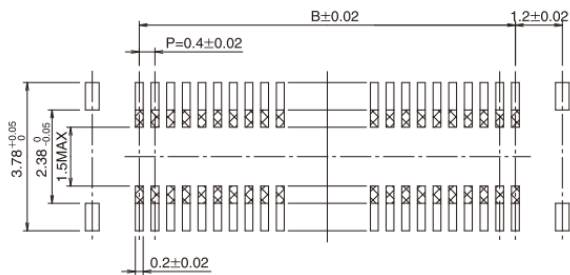
- Male receptacle on SOM : DF40HC(3.0)-100DS-0.4V(51)



◆Recommended PCB layout



DF40HC(Without reinforcing metal fitting)



DF40HB(With reinforcing metal fitting)

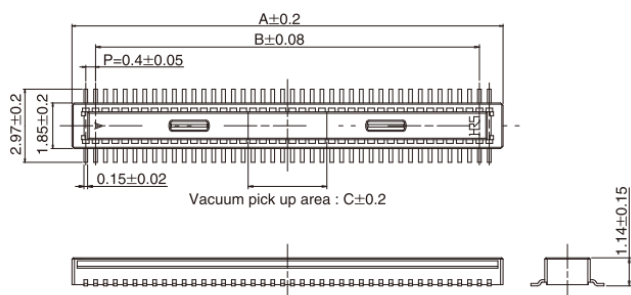
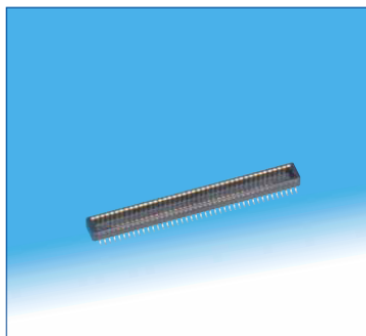
■Stacking height 3.0mm

【Specification No.】
(51) : Embossed package 3,000 pcs/reel

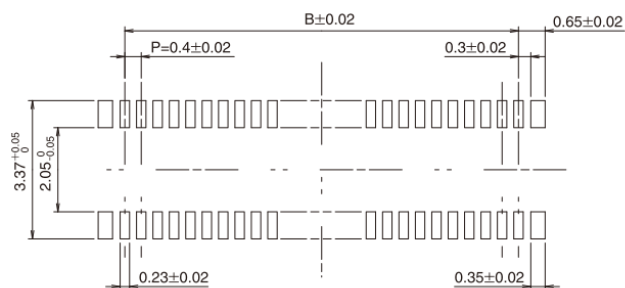
Unit : mm						
Part No.	HRS No.	No. of Contacts	A	B	C	D
DF40HC(3.0)-30DS-0.4V(51)	684-4098-0 51	30	8.6	5.6	1.5	2.9
DF40HC(3.0)-40DS-0.4V(51)	684-4169-6 51	40	10.6	7.6	3.2	
DF40HC(3.0)-44DS-0.4V(51)	684-4076-7 51	44	11.4	8.4		
DF40HC(3.0)-50DS-0.4V(51)	684-4099-2 51	50	12.6	9.6		
DF40HC(3.0)-60DS-0.4V(51)	684-4100-0 51	60	14.6	11.6		
DF40HC(3.0)-70DS-0.4V(51)	684-4138-2 51	70	16.6	13.6		
DF40HC(3.0)-80DS-0.4V(51)	684-4180-9 51	80	18.6	15.6		
DF40HC(3.0)-90DS-0.4V(51)	684-4161-4 51	90	20.6	17.6		
DF40HC(3.0)-100DS-0.4V(51)	684-4151-0 51	100	22.6	19.6		

- Female receptacle on Carrier Board: DF40C-100DP-0.4V(51)

Header



Recommended PCB layout



Unit : mm

Part No.	HRS No.	No. of Contacts	A	B	C
DF40C-10DP-0.4V(51)	684-4035-0 51	10	3.52	1.6	1.0
DF40C-12DP-0.4V(51)	684-4149-9 51	12	3.92	2.0	
DF40C-20DP-0.4V(51)	684-4010-9 51	20	5.52	3.6	
DF40C-24DP-0.4V(51)	684-4011-1 51	24	6.32	4.4	1.2
DF40C-30DP-0.4V(51)	684-4012-4 51	30	7.52	5.6	1.5
DF40C-34DP-0.4V(51)	684-4024-3 51	34	8.32	6.4	2.3
DF40C-40DP-0.4V(51)	684-4013-7 51	40	9.52	7.6	3.2
DF40C-44DP-0.4V(51)	684-4077-0 51	44	10.32	8.4	
DF40C-50DP-0.4V(51)	684-4014-0 51	50	11.52	9.6	
DF40C-60DP-0.4V(51)	684-4003-3 51	60	13.52	11.6	
DF40C-70DP-0.4V(51)	684-4015-2 51	70	15.52	13.6	
DF40C-80DP-0.4V(51)	684-4001-8 51	80	17.52	15.6	
DF40C-90DP-0.4V(51)	684-4125-0 51	90	19.52	17.6	
DF40C-100DP-0.4V(51)	684-4032-1 51	100	21.52	19.6	

IV. Electrical Characteristics

Item	Features
Operational Temperature	-20℃ ~ +80℃
Storage Temperature	-20℃ ~ +90℃
Humidity	5%~90%, non-condensation
Dimensions of SOM	40mm*47mm , 8-layer high precision immersion gold process
Dimensions of Carrier Board	125mm*180mm, 4-layer high precision immersion gold process
Power consumption of whole board	<1.3W (Non-loaded)
Power Supply	DC12V/2.5A

V.Remark

- Under these circumstances, we do not offer repair for free:
- Over warranty time;
- Do not attach purchase receipt;
- Liquid inlet, damp or mold;
- Malfunction and damage is not due to product quality but drops, intense sharking, arbitrarily modify, disoperation after purchase;
- Damage of force majeure.

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